

TC7304A

LTCC

Description

TC7304A is a pure Ag via fill which provides excellent compatibility with Heraeus tape system of CT700 and CT800 during the co-firing process.

Key Features

- Optimized for stencil printing of vias
- Compatible with other co-firing pastes and with various post firing pastes
- After firing, the paste can easily be soldered

Typical Properties

Viscosity	200-300 Pas (25 °C, D = 15/s)
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Metal	Ag
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Recommended Processing Guide

Process Temperature (TDS)	Fire at 850-865 °C (peak) for up to 30 minutes, and with a total firing cycle time up to 10 hours (most often practicable in a box oven).
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